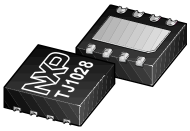


SOT782-2

plastic thermal enhanced very thin small outline package; no leads; 8 terminals

10 June 2016

Package information

1. Package summary

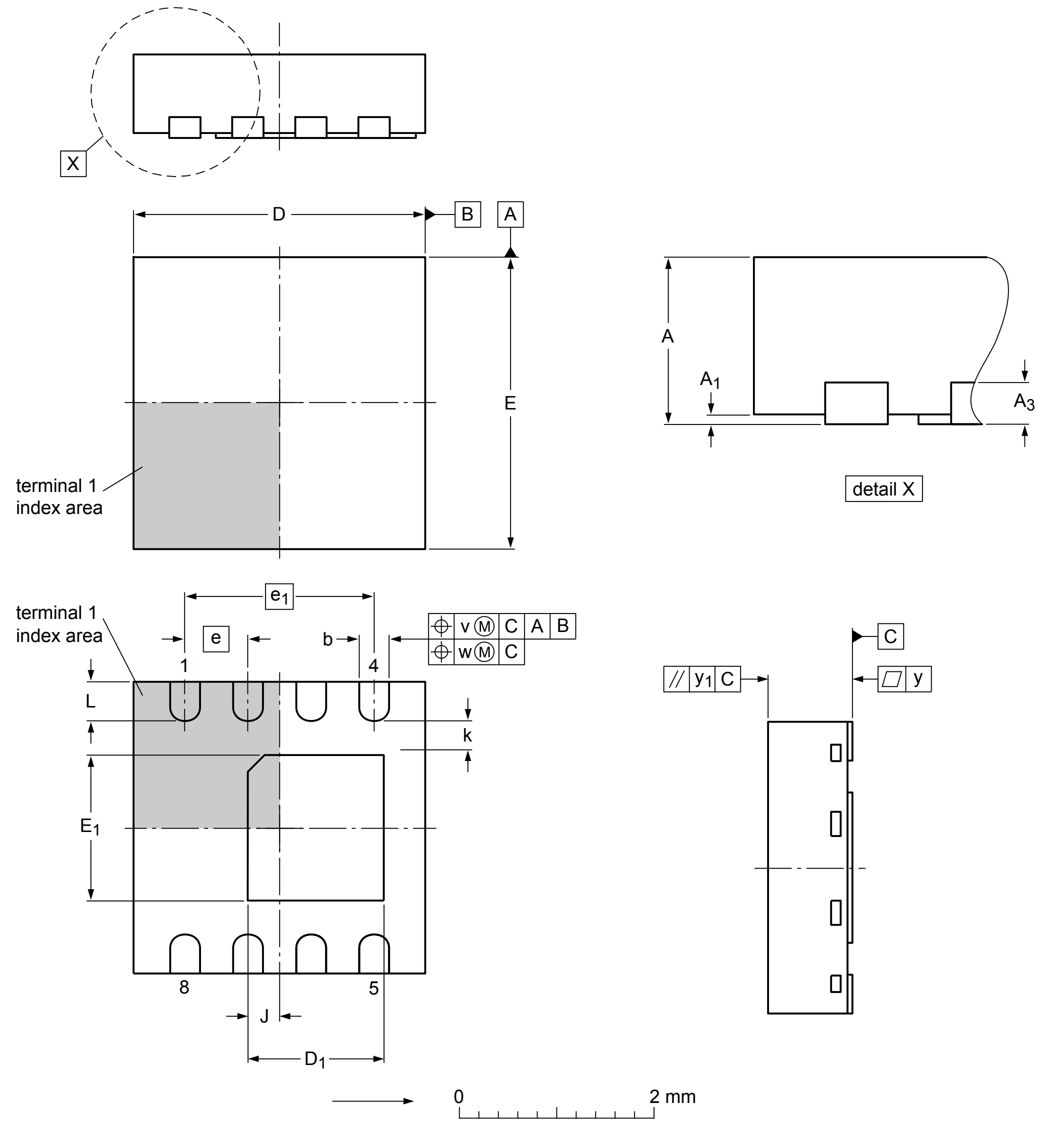
Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	30-8-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.9	-	3	3.1	mm
E	package width		2.9	-	3	3.1	mm
A	seated height		0.8	-	0.85	1	mm
e	nominal pitch		-	-	0.65	-	mm
n_2	actual quantity of termination		-	-	8	-	

2. Package outline

HVSON8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 x 3 x 0.85 mm **SOT782-2**



Dimensions

Unit		A	A_1	A_3	b	D	D_1	E	E_1	J	k	L	e	e_1	v	w	y	y_1
	max	1.00	0.05		0.35	3.10	1.45	3.10	1.55			0.45						
mm	nom	0.85	0.03	0.2	0.32	3.00	1.40	3.00	1.50	0.33		0.40	0.65	1.95	0.1	0.05	0.05	0.1
	min	0.80	0.00		0.29	2.90	1.35	2.90	1.45		0.2	0.35						

Note
1. Plastic or metal protrusions of 0.075 maximum per side are not included.

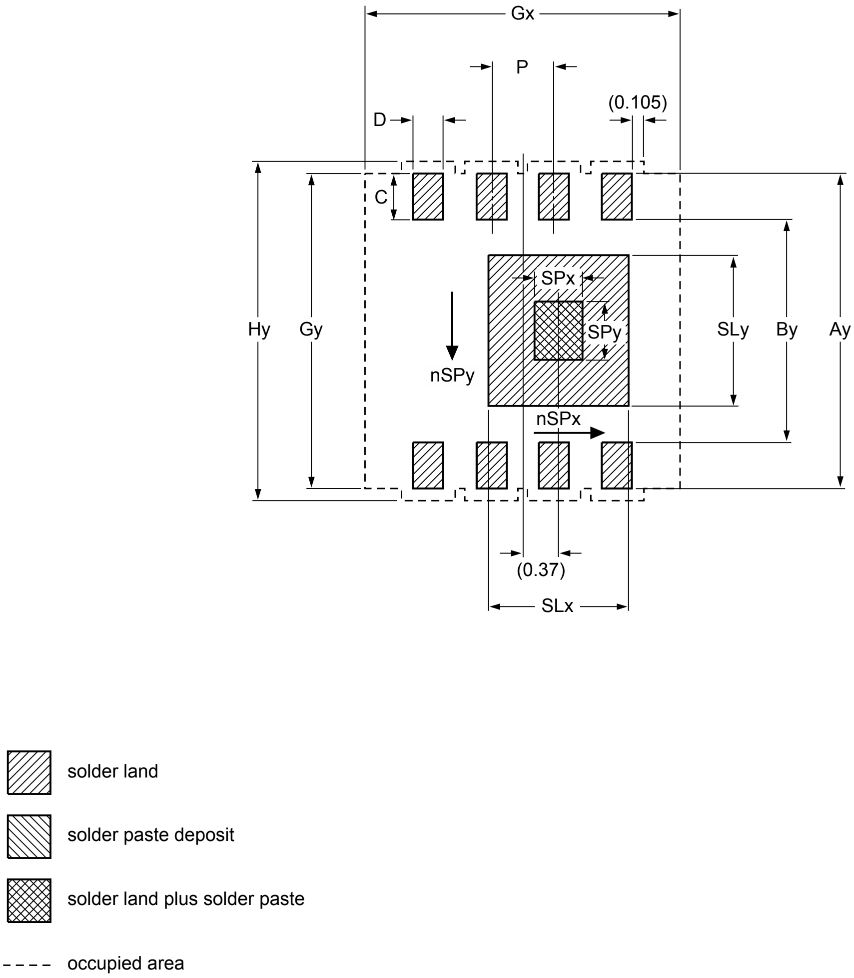
sot782-2_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT782-2		MO-229				~~11-08-29~~ 11-10-03

Fig. 1. Package outline HVSON8 (SOT782-2)

3. Soldering

Footprint information for reflow soldering of HVSON8 package **SOT782-2**



DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx	SPy	Gx	Gy	Hy
0.65	3.25	2.30	0.47	0.30	1.45	1.55	0.50	0.60	3.25	3.25	3.50

nSPx	nSPy
1	1

Issue date ~~11-09-13~~
11-09-27

sot782-2_fr

Fig. 2. Reflow soldering footprint for HVSON8 (SOT782-2)

4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

5. Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 10 June 2016